

AMENDMENTS

In the Claims:

1-49. (cancelled)

50. (currently amended) A process for forming a ~~patterned~~ thin film structure on a substrate, comprising:

printing on the substrate with a ~~printable~~ first material a pattern that defines the area where the thin film structure is to be formed by comprising a positive image thereof of the thin film structure such that the ~~printable~~ first material is printed in the area where the thin film structure is to be formed, the ~~printable~~ first material being strippable using a first solvent;

overcoating the printed surface of the substrate with a second material that is not strippable using the first solvent;

stripping the first material away using the first solvent in a process that strips away the first material and ~~any portions~~ of the second material formed on the first material without stripping away ~~the portions~~ of the second material formed directly on the substrate, such that the second material remains coated on ~~the portions~~ of the substrate where the first material was not present, thereby defining the boundaries of the thin film structure by comprising a negative image thereof of the thin film structure such that the second material is not present in ~~and the first material has been stripped from~~ the area where the thin film structure is to be formed;

depositing a thin film ~~layer~~ material on the patterned top surface of the substrate; and

stripping the second material and the thin film material deposited on the second material to form the thin film structure.

51. (currently amended) The process for forming a ~~patterned~~ thin film structure on a substrate as recited in claim 50, wherein the first material repels the second material ~~such~~ that the second material fills in the areas of the substrate ~~between the areas~~ where the first material has not been printed without coating the areas where the first material is present.

52. (currently amended) The process for forming a ~~patterned~~ thin film structure on a substrate as recited in claim 50, wherein the first solvent is an aqueous solution or water.

53. (withdrawn and currently amended) The process for forming a ~~patterned~~ thin film structure on a substrate as recited in claim 50, wherein the first solvent is a non-aqueous solvent or solution.

54. (currently amended) The process for forming a ~~patterned~~ thin film structure on a substrate as recited in claim 50, wherein the first solvent is an aqueous basic solution, and the step of stripping the second material comprises using a second solvent comprising an aqueous acidic solution, an aqueous neutral solution, or water.

55. (currently amended) The process for forming a ~~patterned~~ thin film structure on a substrate as recited in claim 50, wherein the first solvent is an aqueous acidic solution and the step of stripping the second material comprises using a second solvent comprising an aqueous basic solution, an aqueous neutral solution, or water.

56. (currently amended) The process for forming a ~~patterned~~ thin film structure on a substrate as recited in claim 50, wherein the first solvent is an aqueous neutral solution or water and the step of stripping the second material comprises using a second solvent comprising an aqueous acidic solution or an aqueous basic solution.

57-66. (cancelled)